





NDT

Electronics Food

Inline Inspection

# FAST INDUSTRIAL DUAL ENERGY PHOTON COUNTING DETECTOR

The TDI range of photon counting detectors are ideal for line scan applications demanding high speed inspection and optional dual energy capability. The technology enables high spatial resolution even at fast scanning speeds with the ability to differentiate between subject materials.

The extreme sensitivity combined with efficient TDI scanning maximises the use of available X-rays in generating high quality images thereby decreasing X-ray tube power requirements. The radiation hardness of CdTe supports reliability and a long lifetime.

# FEATURES

Dual energy imaging for material discrimination

Different energy range options

High speed inspection

Lower X-ray source power requirement

High resolution images

Noise free read-out

Low-dose

Long lifetime

@DirectConv in

# **TECHNICAL SPECIFICATIONS**

Direct Conversion X-ray detectors, unless specified otherwise, are components intended to be integrated into products by X-ray system manufacturers.

System manufacturers are responsible for qualifying and validating their products for their intended uses and meeting all applicable regulatory requirements.

SENSOR



#### XC-TDI 100x6 150x6 200x6 350x6 500x6 650x6 1000x6 ACTIVE AREA 102 x 6 154 x 6 205 x 6 359 x 6 513 x 6 688 x 6 1027 x 6 E x D mm<sup>2</sup> PHYSICAL DIMENSIONS 120 x 277 120 x 277 120 x 277 120 x 428 120 x 585 120 x 739 120 x 1098 x 66 [1] WEIGHT (kg) [2] 3.0 - 3.5 3.0 - 3.5 3.0 - 3.5 5.0 - 5.8 7.2 - 8.0 16.5 - 17.0 9.0 - 10.01027 x 60 PIXEL MATRIX 2055 x 60 3597 x 60 5139 x 60 10279 x 60 1541 x 60 6681 x 60 MAX SPEED (lps) [3] 20000 20000 20000 15000 20000 19000 9000 POWER 120 120 120 170 240 300 480 CONSUMPTION (w) ENERGY RANGE (kVp) 100L = 20 - 100 Ø Ø 0 Ø Ø Ø ŏ 160 = 40 - 160 0 Ø Ø 0 Ø 0 300 = 40 - 300 Õ Õ Õ VARIANTS A = Fan Cooling Ø Ø Ø Ø Ø Ø Ø ŏ ŏ ŏ Õ B = No Fans Ø [1] [2] [3] Excluding fans which add Depends on the energy 33 mm to thickness C range and options

VAREX IMAGING COMPANY

Continuous 8-bit single-energy scanning at 25 % active time. Burst speed might be higher. Pixel binning and cropping can increase the maximum speed as well as reducing the active time

## COMMUNICATIONS

Data Interface	1000Base-T
Power Supply	12 VDC
External Trigger Signals	Opto-coupled 12-24V Start, Encoder
REGULATORY	
EU/CE	IEC/EN 60601-1:2012

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Ingress Protection	IP20
Operating Temperature	0 to +35 °C
<b>Operating Humidity</b> Non-condensing	30 to 55 %
Storage Temperature	-10 to +50 °C
Storage Humidity Non-condensing	10 to 95 %

02.10011	
Technology	Photon Counting Dual Energy
Modes	Single Energy High Speed TDI Dual Energy High Speed TDI Dual Energy Spectral TDI
Converter	Cadmium Telluride (CdTe)
Pixel Pitch	100 µm
Pixel Fill-factor	100 %
Tile Gap	100 µm
<b>Count Rate</b> High Speed Modes Spectral Mode	200 Mcnts / s / mm² 20 Mcnts / s / mm²
Pixel Depth	up to 18 bits / frame
Active Area	See PRODUCT RANGE
Imaging Speed	See PRODUCT RANGE
Binning	2x2, 4x4
Temperature Control	Integrated thermo-electric with a PWM controlled fan

IMAGE QUALITY *	High Speed	Spectral
MTF @ 1.0 lp / mm	95 %	90 %
MTF @ 2.5 lp / mm	70 %	70 %
MTF @ 4.0 lp / mm	50 %	60 %
DQE @ 1.0 lp / mm	70 %	75 %
DQE @ 2.5 lp / mm	55 %	55 %
DQE @ 4.0 lp / mm	40 %	35 %
Lag	(aft	0 % er X-ray 6 μGy)
Ghosting	(1 n	< 0.1 % nin after 6 µGy)

\* Typical values (actual values depend on configuration)

### MATERIALS

SDK

Operating System

Energy Range	Housing	X-Ray Window		
100L	AI/Cu	AI Coated Polymer		
160	AI/Cu	Carbon Fiber		
300	AI/Wcu	Carbon Fiber		
SOFTWARE INTERFACE				
Direct		UDP Based		



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Windows 7 (onwards)